Title (en)

METHOD FOR PRODUCING A MICROMECHANICAL COMPONENT AND THE THUS OBTAINED MICROMECHANICAL COMPONENT

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES MIKROMECHANISCHEN BAUELEMENTS SOWIE MIKROMECHANISCHES BAUELEMENT

Title (fr)

PROCEDE DE FABRICATION D'UN COMPOSANT MICROMECANIQUE ET COMPOSANT MICROMECANIQUE AINSI OBTENU

Publication

**EP 1899260 A1 20080319 (DE)**

Application

**EP 06754905 A 20060427**

Priority

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Abstract (en)

[origin: WO2007000363A1] The invention relates to a micromechanical method for producing a cavity in a substrate and, in particular a micromechanical component produced according to said method. The inventive method comprises a first step consisting in producing a first layer on a substrate or therein, in applying at least one second layer to the first layer and in producing an input hole in the said second layer in such a way that the first layer and substrate materiel is removable therethrough. Said second layer arranged above the cavity and can be subsequently used in the form of a membrane. It is also possible to apply other layers to the second layer, in such a way that they form a whole membrane, only. According to the main aspect of the invention, the first layer material is selected in such a way that a transition edge is produced in the first layer by removing the material thereof and is provided with an predeterminable angle between the substrate and the second layer.

IPC 8 full level

**B81C 1/00** (2006.01)

CPC (source: EP US)

**B81C 1/00595** (2013.01 - EP US); B81B 2203/0315 (2013.01 - EP US); Y10T 428/24562 (2015.01 - EP US)

Citation (search report)

See references of WO 2007000363A1

Citation (examination)

YOUNG H. LEE ET AL: "Silicon Etching Mechanisms - Doping Effect", MRS PROCEEDINGS, vol. 38, 1 January 1984 (1984-01-01), XP055255387, DOI: 10.1557/PROC-38-163

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